L Number	Hits	Search Text	DB	Time stamp
1	367	- 1 · 1 · 1 · 1 · 1 · 1 · 1 · 1 · 1 · 1	USPAT;	2003/09/16
		(gap or space or hole or spaces or	US-PGPUB;	12:10
		spacing or slit or crack or cut or groove or slot or dam or open or opening))	EPO; JPO; DERWENT;	
l	l	or side of dam of open of opening,	IBM TDB	
2	231	1 (== -, -, -, -, -, -, -, -, -, -, -, -, -,	USPAT;	2003/09/16
	,	(gap or space or hole or spaces or	US-PGPUB;	12:57
		spacing or slit or crack or cut or groove or slot or dam or open or opening))) and	EPO; JPO; DERWENT;	
		(@ad<20000512)	IBM TDB	
3	9395	(chip or die or electronic or device or	USPAT;	2003/09/16
1	1	semiconductor) and (((substrate or board	US-PGPUB;	12:36
		or carrier) and (ball or bump or solder)) with (recess or trench or groove or	EPO; JPO; DERWENT;	
1		depression or via))	IBM TDB	
4	6368	((chip or die or electronic or device or	USPAT;	2003/09/16
		semiconductor) and (((substrate or board	US-PGPUB;	12:35
		or carrier) and (ball or bump or solder))	EPO; JPO;	
		with (recess or trench or groove or depression or via)) ) and (@ad<20000512)	DERWENT;	
5	310	(((chip or die or electronic or device or	USPAT;	2003/09/16
		semiconductor) and (((substrate or board	US-PGPUB;	12:53
		or carrier) and (ball or bump or solder))	EPO; JPO;	
		with (recess or trench or groove or depression or via)) ) and (@ad<20000512))	DERWENT;	
İ		and (solder adj joint)	IBM_TDB	
6	63	((((chip or die or electronic or device	USPAT;	2003/09/16
		or semiconductor) and (((substrate or	US-PGPUB;	12:57
		board or carrier) and (ball or bump or	EPO; JPO;	
		solder)) with (recess or trench or groove   or depression or via)) ) and	DERWENT;	
		(@ad<20000512)) and (solder adj joint))	IBM_TDB	
		and ((vent or air or escape or gas) with		
		(solder or joint or hole or groove or		
		slit or slot or crack or opening or open or space or spacing or spaces or groove))		
7	48	(((chip or die or electronic or device or	USPAT;	2003/09/16
		semiconductor) and (((substrate or board	US-PGPUB;	12:56
		or carrier) and (ball or bump or solder))	EPO; JPO;	
		with (recess or trench or groove or	DERWENT;	
		depression or via)) ) and (@ad<20000512)) and ((solder adj joint) with (increase or	IBM_TDB	
		enhance or strengthen or strength))		
8	30	((((chip or die or electronic or device	USPAT;	2003/09/16
		or semiconductor) and (((substrate or	US-PGPUB;	12:54
	l	board or carrier) and (ball or bump or solder)) with (recess or trench or groove	EPO; JPO; DERWENT;	
		or depression or via)) ) and	IBM TDB	
		(@ad<20000512)) and ((solder adj joint)		
	i	with (increase or enhance or strengthen		
		or strength))) not (((((chip or die or electronic or device or semiconductor)		
		and (((substrate or board or carrier) and		
		(ball or bump or solder)) with (recess or		
		trench or groove or depression or via)))		
		and (@ad<20000512)) and (solder adj joint)) and ((vent or air or escape or		
		gas) with (solder or joint or hole or		
		groove or slit or slot or crack or		
		opening or open or space or spacing or		
	222	spaces or groove)))	ticp.» m	2007/00/26
9	289	<pre>((substrate or board or carrier) with (chip or die or device or semiconductor))</pre>	USPAT; US-PGPUB;	2003/09/16   12:57
		and ((solder adj joint) with (increase or	EPO; JPO;	14.57
		enhance or strengthen or strength))	DERWENT;	
			IBM TDB	

10	231	((257/778.ccls. and ((pad or land) with	USPAT;	2003/09/16
		(gap or space or hole or spaces or	US-PGPUB;	12:57
		spacing or slit or crack or cut or groove	EPO; JPO;	
		or slot or dam or open or opening))) and	DERWENT;	
		(@ad<20000512)) and (@ad<20000512)	IBM TDB	
11	32	(((257/778.ccls. and ((pad or land) with	USPĀT;	2003/09/16
	ļ	(gap or space or hole or spaces or	US-PGPUB;	12:58
		spacing or slit or crack or cut or groove	EPO; JPO;	
		or slot or dam or open or opening))) and	DERWENT;	
1		(@ad<20000512)) and (@ad<20000512)) and	IBM TDB	
		((air or escape or gas) with (vent or	_	
1		solder or joint or hole or groove or slit		
		or slot or crack or opening or open or		
		space or spacing or spaces or groove))		